

Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
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EFS ID: 53693

Application ID: 10667227



Title of Invention:

SEMICONDUCTOR PACKAGE AND  
METHOD OF MAKING  
LEADFRAME HAVING LEAD  
LOCKS TO SECURE LEADS TO  
ENCAPSULANT

First Named Inventor: Jae Yee

Domestic/Foreign Application: Domestic Application

Filing Date: 2003-09-18

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Submission Type: Information Disclosure  
Statement

Filing Type:

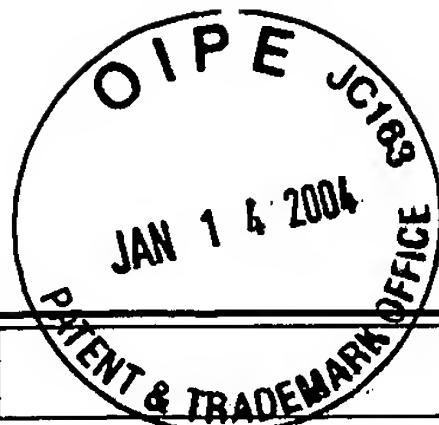
Confirmation number: 7012

Attorney Docket Number: AMKOR012G1

Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark  
Office,ou=Department of Commerce,o=U.S. Government,c=US


Certificate Message Digest: 29b69d095b53938804d095c9bc851d88f9d5be9d

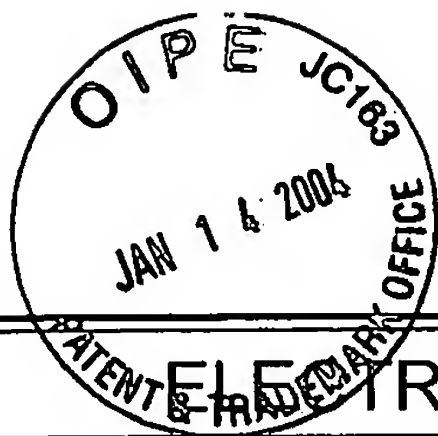


## TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT									
Application Number: 10/667227 										
Date: 2003-09-18										
First Named Applicant: Jae Hak Yee										
Confirmation Number: 7012										
Attorney Docket Number: AMKOR012G1										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
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Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids4-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids4-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids4-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18  
Stylesheet Version v18.0

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Application Number: 10/667227  
Confirmation Number: 7012  
First Named Applicant: Jae Yee  
Attorney Docket Number: AMKOR012G1  
Art Unit: 2812  
Search string: ( 5903049 or 5909053 or 5917242 or 5915998  
or 5939779 or 5942794 or 5951305 or 5959356  
or 5969426 or 5973388 or 5977630 or 5977615  
or 5977613 or 5976912 or 5981314 or 5986885  
or 5986333 or 6001671 or 6013947 or 6018189  
or 6020625 or 6025640 or 6031279 or 6034423  
or RE36613 or 6040626 or 6043430 or 6060769  
or 6060768 or 6072228 or 6075284 or 6081029  
or 6084310 or 6087722 or 6087715 or 6100594  
or 6113474 or 6118184 or 6118174 or RE36907  
or 6130473 or 6130115 or 6133623 or 6140154  
or 6143981 or 6169329 or 6177718 or 6181002  
or 6184573 or 6184465 ).pn.



US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5903049	1999-05-11	MORI			
	2	5909053	1999-06-01	FUKASE ET AL.			
	3	5917242	1999-06-29	BALL			
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	10	5973388	1999-10-26	CHEW ET AL.
	11	5977630	1999-11-02	WOODWORTH ET AL.
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	48	6181002	2001-01-30	JUSO ET AL
	49	6184573	2001-02-06	PU
	50	6184465	2001-02-06	CORISIS

Signature

Examiner Name	Date